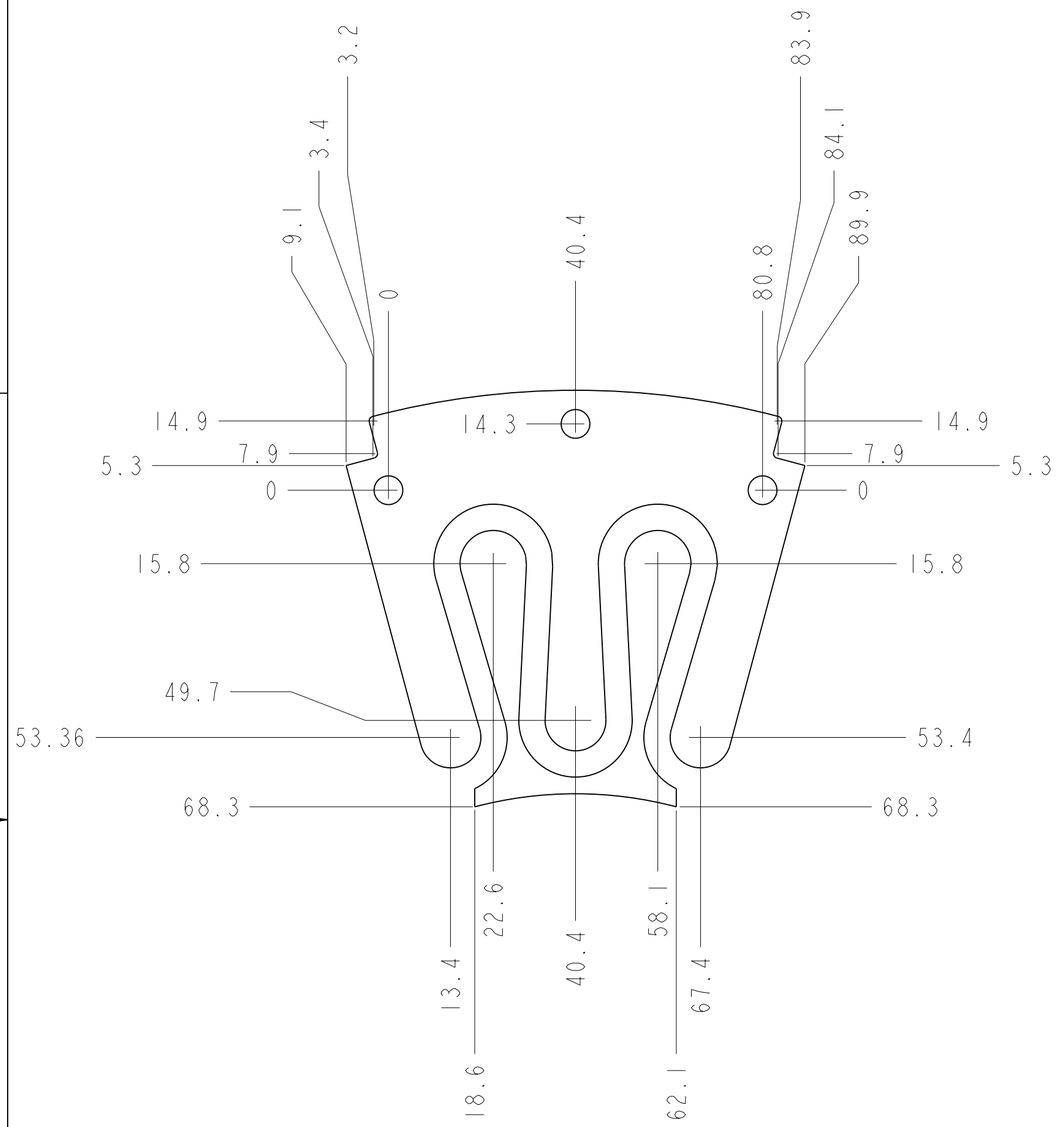
DESCRIPTION	MATERIAL	MAT. LOCATION
	BRYTE E01189-2M	-



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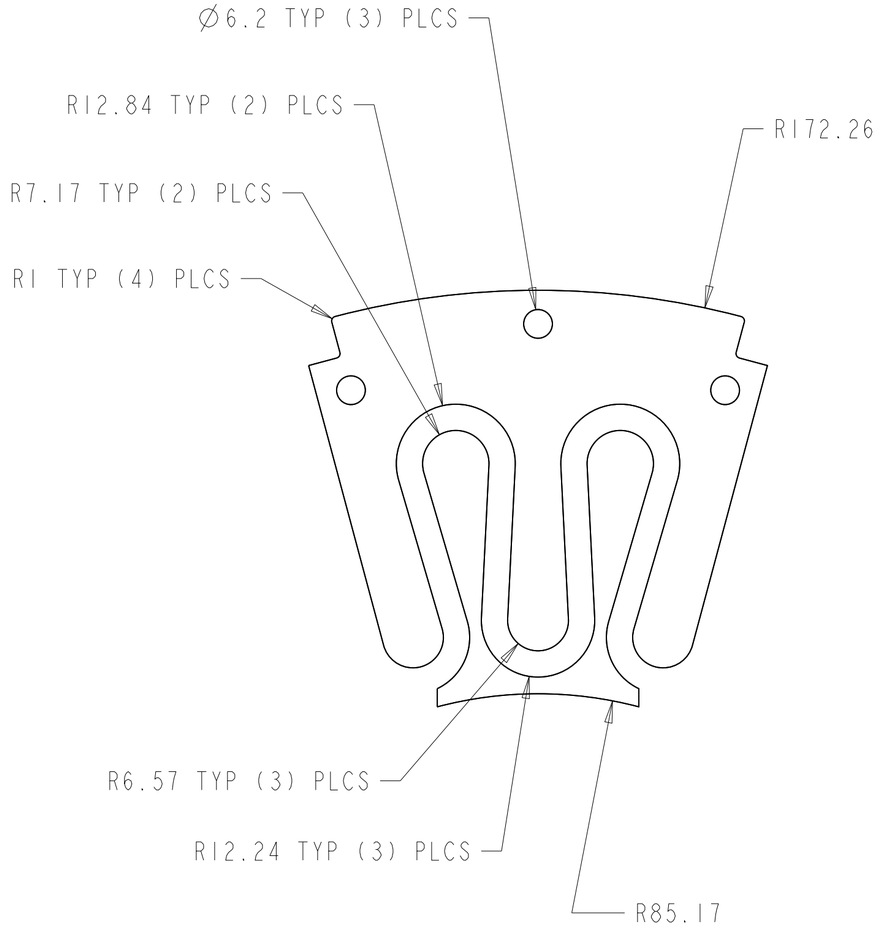

DWG. NO. 21f4253 | SIZE | REV. | SH.: 1 | 1

REV	DWG	CHK	ZONE	DATE	CHANGES

UNLESS OTHERWISE SPECIFIED

TOLERANCES		
	X.X ± 0.1	FRAC. ± 1/64
	X.XX ± 0.01	Angles ± 0.50°
	X.XXX ± 0.001	FINISH 125 (µin)

DO NOT SCALE PRINT

THREADS ARE CLASS 2

CHAMFER ENDS OF ALL SCREW TREADS 30°

CUT ROUND, 1.5 THREAD RELIEF ON MACHINED THREADS

BREAK EDGES .016 MAX. ON MACHINED WORK

REMOVE BURRS, WELD SPLATTER & LOOSE SCALE

IN ACCORDANCE WITH ASME Y14.5M & B46.1

SHOP ORDERS

ACCT NO.	See J.O.	NO. REQD 60	
DEL TO	Jon Wirth		
SURFACE TREATMT			
IDENT METHOD	TAG		
PROJECT NUMBER	ATL-IP-ED-0032		US ATLAS SILICON SUBSYSTEM (logo)
PROJECT NAME	US ATLAS SILICON SUBSYSTEM		
DWG BY	D UKEN	DATE 19-JUN-01	
CHK BY	J WIRTH	DATE 29-JUN-01	
APR BY	E ANDERSSEN	DATE	

SER NO. -

DATE ISSD -

DATE REQD -

ERNEST ORLANDO LAWRENCE BERKELEY NATIONAL LABORATORY

UNIVERSITY OF CALIFORNIA - BERKELEY

ATLAS PIXEL DETECTOR

DISK SECTOR, MODULE LOCAL SUPPORT

CYANATE ESTER FOR FOAM

MICROFILMED:	DWG. TYPE	SHOWN ON	SCALE: 1.000 DO NOT SCALE PRINTS
	PART	21F350	SHEET 1 OF 1
PATENT CLEAR:	DESIGN ACCT. NO.	CATEGORY CODE	DWG. NO. 21f4253 SIZE D REV. 1
	SEE J.O.	AP6110	

Dwg. File: 21f425 Model File: 21f425

Rev. 1/8/2001 ATLAS